

23343

**M. Tech. 2nd Semester (Embedded System and Design)**

**Examination, May–2015**

**LOW POWER VLSI DESIGN**

**Paper–MT-VLES-506**

*Time allowed : 3 hours]*

*[Maximum marks : 100*

---

*Note : Attempt any five questions.*

1. (a) What are the basic needs for Low Power VLSI Chips ? Explain. 10
- (b) What is power dissipation in CMOS devices ? Explain in detail. 10
2. (a) What is technology scaling ? Explain the effect of technology scaling on power. 10
- (b) What is transistor sizing and gate oxide thickness ? Explain. 10
3. (a) Explain the low power design circuit of flip-flop in-detail. 10
- (b) What are different types of limits used in designing of low power VLSI chips ? Explain. 10
4. (a) Discuss the state machine encoding and pre-computation logic in detail. 10
- (b) What is low power memory design used in VLSI ? Explain. 10

( 2 )

**23343**

5. Differentiate between following : 20
- (i) Single drive Vs. distributed buffer used in VLSI.
  - (ii) Zero skew Vs. tolerable skew.
6. (a) Explain the design flow used in VLSI Chips. How it will be optimized ? 10
- (b) Derive the V-I characteristics and required current equation used in MOSFET. 10
7. What is low power architecture and system ? Explain. How performance of this will be managed ? 20
8. What are the algorithm and architecture level methods ? Explain the different methodologies being used. 20